

AN4849

Four injector and fuel pump drive

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Application note

Document information

Information	Content
Keywords	MC33816, PT2001, injector, fuel pump, automotive
Abstract	Example of a four cylinder internal combustion engine (ICE) injector drive.



1 Introduction

This typical application covers an example of a four cylinder internal combustion engine (ICE) injector drive. A boost converter managed by the MC33816/PT2001 provides the high voltage.

This application covers both MC33816 and PT2001 devices. Reuse similar code and registers for both devices. HW and SW are 100 % compatible.

2 Overview

This overview presents a typical hardware topology and related software example to drive four injectors managed in two banks, a single low-pressure pump drive, and a variable frequency modulation (VFM) DC-to-DC converter.

A battery voltage between 9.0 V and 16 V supplies the MC33816. A battery voltage between 5 V and 24 V supplies the PT2001. Consider a protection circuitry against overvoltage and reverse battery on the V_{BAT} supply line.

To supply internally the I/O buffers, supply an external 5.0 V to the VCC5 pin and the VCCIO pin.

In this example, generate the V_{CCP} voltage internally to enable the drivers.

To manage a VFM, define the boost converter topology. A pi filter prevents circuitry disturbance propagation from the boost regulation area to battery line.

The two banks can manage two injectors each. In this configuration, injection overlaps are not possible inside a bank. The diodes D12, D13, D14, and D15 are required to allow current recirculation when the respective low-side metal-oxide-semiconductor field-effect transistors (MOSFETs) are switched off. The diodes D10_2 and D11_2 provide a current recirculation path to ground when the respective high-side MOSFET is off.

3 Application schematic

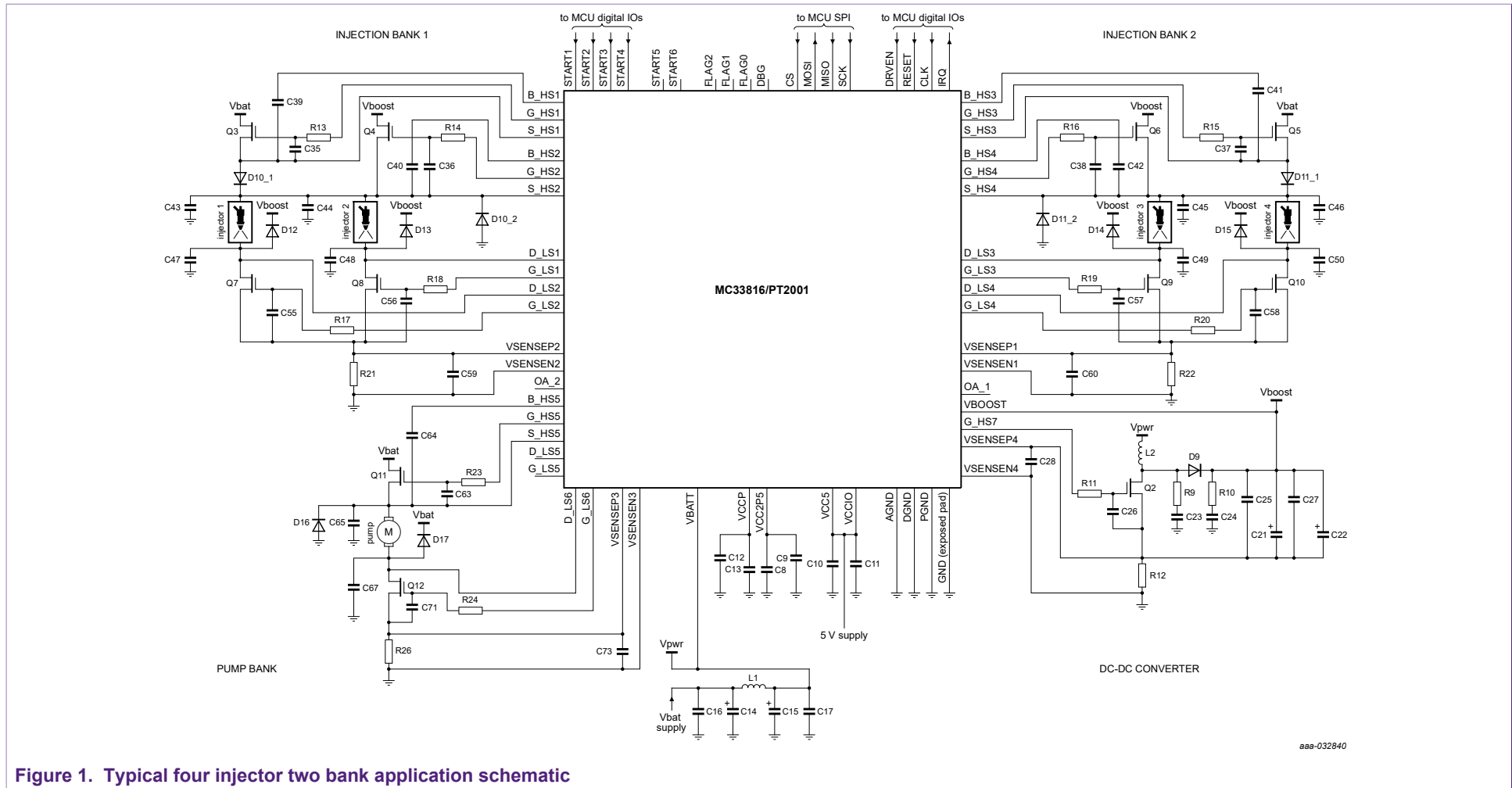


Figure 1. Typical four injector two bank application schematic

4 Application instructions

This topology can be used on the evaluation board KIT33816FRDMEVM or KITPT2001FRDMEVM. Register settings and microcode downloads can be achieved by using the KL25Z embedded on the KIT33816FRDMEVM or KITPT2001FRDMEVM.

This topology allows managing two banks of two cylinders. Injector actuations are limited to one injection per bank at the same time. Each bank is individually managed by one microcore of the digital channel 1 as described next:

- The bank # 1 is managed by the digital microcore Uc0Ch1.
- The bank # 2 is managed by the digital microcore Uc1Ch1.

The two microcores of the second channel (Channel 2) drive the VFM and the fuel pump as described next:

- The VFM is managed by the digital microcore Uc0Ch2.
- The fuel pump is managed by the digital microcore Uc1Ch2.

The following is the start-up sequence:

1. Apply a battery voltage between 9.0 V and 16 V.
2. Download the registers Channel Configuration, then Main Configuration, IO Configuration, and Diagnostic Configuration.
3. Download the dedicated microcode in the logic Channel 1 and logic Channel 2 data RAMs.
4. Set to logic 1 to the pre-flash enable bit and the en_dual_seq bit in the Flash_enable register of channel 1 (0x100) and channel 2 (0x120).

The following sections detail the registers configuration and the microcodes.

Once the DC-to-DC converter output has reached its nominal voltage, the STARTx pins can actuate the injector drivers. Each STARTx pin individually triggers each injector pin rising edge and stops actuation on the falling edge.

- START1 drives INJECTOR 1
- START2 drives INJECTOR 2
- START3 drives INJECTOR 3
- START4 drives INJECTOR 4
- START5 drives FUEL PUMP 1

Boost regulation is stopped during the injection boost phase.

5 Software requirements

5.1 Current profile management for injection

The current profile is managed so to generate an initial high current through the injector. This high current slew rate minimizes the opening delay. This high current is maintained during a given time to ensure injector opening. Then the current is decreased to maintain the injector open, up to the end of injection (EOI).

The code dedicated to the injection is loaded into the code RAM 1. This code is executed independently by the microcores Uc0Ch1 and Uc1Ch1. Each one of the microcores generates a current profile, as described through the injector per the STARTx pin state by the following figure.

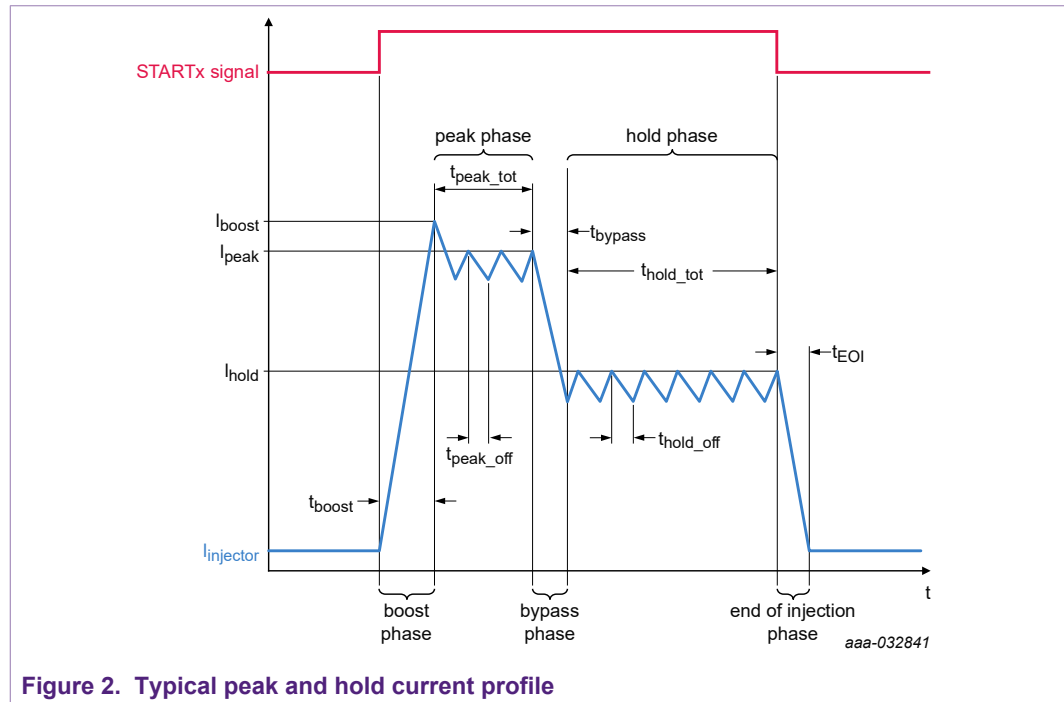


Figure 2. Typical peak and hold current profile

When a rising edge is detected on a STARTx pin, the injection starts with the injection boost phase.

This profile can be stopped at any time by detecting a falling edge on the STARTx pin. In this case, the EOI phase is executed.

During the boost phase, the corresponding low-side driver is simultaneously switched on with the high-side switch connected to the V_{boost} voltage. If the boost current target I_{boost} is reached, the high-side driver is switched off and the current recirculates for a fixed time (t_{peak_off}) through the diode connected to ground. Then the peak phase starts.

During the peak phase, the high-side switch connected to V_{BAT} voltage is turned on. If the peak current target I_{peak} is met, the high-side driver is switched off and the current recirculates through the diode connected ground for the fixed time (t_{peak_off}). The high-side driver is then switched on again. This cycle repeats until that the internal counter reaches its terminal value (t_{peak_tot}), then the bypass phase begins.

During the bypass phase, all the low-side and high-side switches are turned off. The current decays through the injector, the diode connected to ground, and the diode connected to V_{boost} for a fixed time (t_{bypass}). The hold phase then starts.

During the hold phase, the low-side driver is simultaneously switched on with the high-side switch connected to the V_{BAT} voltage. If the hold current target I_{hold} is reached, the high-side driver is switched off and the current recirculates through the diode connected to ground for a fixed time (t_{hold_off}). The high-side driver is switched on again, and the cycle repeats until the STARTx pin goes LOW or the internal counter reaches its terminal value [t_{hold_tot} (timeout)]. The EOI is forced if no falling edge is detected on the STARTx pin.

All the current thresholds and timings are accessed in the data RAM. The typical values are in [Table 1](#), but must be defined according to the injector used and the injection profile expected.

Table 1. Example of injection current profile key parameters ($R_{SENSE} = 10\text{ m}\Omega$)

Parameter name	Description	Value
I_{boost}	current threshold in boost phase	16.72 A
I_{peak}	current threshold in peak phase	16.72 A
I_{hold}	current threshold in hold phase	8.92 A
t_{peak_off}	fixed time for high-side switch off in peak phase	10 μ s
t_{peak_tot}	fixed time for end of peak phase	200 μ s
t_{bypass}	fixed time for bypass phase	30 μ s
t_{hold_off}	fixed time for high-side switch off in hold phase	10 μ s
t_{hold_tot}	fixed time for end of hold phase (timeout)	10 ms

In the present case, most of the code branches (jump) are managed according to the counters end of count and the current threshold, by the mean of the wait table. The wait table rows are affected, as shown in [Table 2](#) and are changed according to the injection phase.

Table 2. Example of wait table definition

Phase	Boost phase	Peak phase	Bypass phase	Hold phase	EOI phase
Row 1	if STARTx goes LOW then jump to EOI phase	if STARTx goes LOW, then jump to EOI phase	if STARTx goes LOW, then jump to EOI phase	if STARTx goes LOW, then jump to EOI phase	-
Row 2	if the injection current reaches I_{boost} then jump to peak phase	if t_{peak_tot} is reached, then jump to bypass phase	if t_{bypass} is reached, then jump to hold phase	if t_{hold_tot} is reached, then jump to EOI phase	-
Row 3	-	if t_{peak_off} is reached, jump to peak on phase (sub phase)	-	if t_{hold_off} is reached, jump to hold on phase (sub phase)	-
Row 4	-	if I_{peak} is reached, jump to hold off phase (sub phase)	-	if I_{hold} is reached, jump to hold off phase (sub phase)	-
Row 5	-	-	-	-	-

A rising edge issues an injection start. A falling edge triggers the end of injection. In case of an overlap between two STARTx pins on the same bank, it is managed by the smart start function of the device. In this case, the first STARTx rising edge is considered. The second STARTx pin high-state is considered when the first actuation is finished. The action of the injection corresponding to the second STARTx pin is stopped when the second STARTx pin falling edge occurs.



Figure 3. Actuation driven by STARTx pins without overlap

5.1.1 General registers setup

The MC33816/PT2001 registers are set up according to their default states, unless defined by the following.

5.1.1.1 Main configuration register

To run two microcores per channel, the Ck_per register (0x1C0) must be set up with a ck_per value of 3 or more.

Table 3. Ck_per register (0x1C0)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	reserved											ck_per				
Value	-											000011				

5.1.2 Injection banks management registers setup

The MC33816/PT2001 registers are set up according to their default states, unless defined by the following.

5.1.2.1 IO configuration registers

The microcore Uc0Ch1 must have access to the pre-drivers HS1, HS2, LS1, and LS2.

Table 4. Out_acc_uc0_ch1 register (0x184)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	reserved				acc_ uc0_ ch1_ ls7	acc_ uc0_ ch1_ ls6	acc_ uc0_ ch1_ ls5	acc_ uc0_ ch1_ ls4	acc_ uc0_ ch1_ ls3	acc_ uc0_ ch1_ ls2	acc_ uc0_ ch1_ ls1	acc_ uc0_ ch1_ hs5	acc_ uc0_ ch1_ hs4	acc_ uc0_ ch1_ hs3	acc_ uc0_ ch1_ hs2	acc_ uc0_ ch1_ hs1
Value	0000				0	0	0	0	0	1	1	0	0	0	1	1

In the same way, the Uc1Ch1 must have access to the pre-drivers HS3, HS4, LS3, and LS4.

Table 5. Out_acc_uc1_ch1 register (0x185)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	reserved				acc_ uc1_ ch1_ ls7	acc_ uc1_ ch1_ ls6	acc_ uc1_ ch1_ ls5	acc_ uc1_ ch1_ ls4	acc_ uc1_ ch1_ ls3	acc_ uc1_ ch1_ ls2	acc_ uc1_ ch1_ ls1	acc_ uc1_ ch1_ hs5	acc_ uc1_ ch1_ hs4	acc_ uc1_ ch1_ hs3	acc_ uc1_ ch1_ hs2	acc_ uc1_ ch1_ hs1
Value	0000				0	0	0	1	1	0	0	0	1	1	0	0

The microcore Uc0Ch1 has default access to the current sense block # 1, and to microcore Uc1Ch1 to the current sense block # 2. The corresponding registers content does not need to be changed.

Table 6. Cur_block_access_1 register (0x188)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	reserved						acc_ uc1_ ch1_ curr_ 4h_ 4neg	acc_ uc1_ ch1_ curr4l	acc_ uc1_ ch1_ curr3	acc_ uc1_ ch1_ curr2	acc_ uc1_ ch1_ curr1	acc_ uc0_ ch1_ curr_ 4h_ 4neg	acc_ uc0_ ch1_ curr4l	acc_ uc0_ ch1_ curr3	acc_ uc0_ ch1_ curr2	acc_ uc0_ ch1_ curr1
Value	000000						0	0	0	1	0	0	0	0	0	1

5.1.2.2 Channel 1 configuration registers

The banks 1 and 2 are driven according to the logic level of their respective STARTx pin. A HIGH level on STARTx triggers the activation of the corresponding injector. A LOW level on the STARTx pin automatically stops the actuation, whatever the injection phase.

The microcore Uc0Ch1 must be enabled by the START1 and START2 pins, while the microcore Uc1Ch1 must be enabled by the START3 and START4 pins.

Consequently, the Start_config_reg register of the channel 1 (0x104) must be set up, as shown in [Table 7](#).

Table 7. Start_config_reg registers (0x124)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	reserved		smart_start_uc1	smart_start_uc0	start6_sens_uc1	start5_sens_uc1	start4_sens_uc1	start3_sens_uc1	start2_sens_uc1	start1_sens_uc1	start6_sens_uc0	start5_sens_uc0	start4_sens_uc0	start3_sens_uc0	start2_sens_uc0	start1_sens_uc0
Value	00		0	0	0	0	1	1	0	0	0	0	0	0	1	1

The Code_width register and the two checksum value registers must be set to verify permanently the code integrity. The checksum is recalculated in the MC33816/PT2100 at runtime each time a microcode line is executed and compared to the checksum register value. If there is a mismatch, an error is reported.

Table 8. Code_width registers (0x107)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	reserved						code_width									
Value	-						0001011000									

Table 9. Checksum_h registers (0x108)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	checksum_high															
Reset	1000111001100010															

Table 10. Checksum_l registers (0x109)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	checksum_low															
Reset	0111101100100011															

The code entry point of Uc0Ch1 is 0 as the first line executed, is the first code RAM line of the channel 1.

Table 11. Uc0_entry_point registers (0x10A) of channel 1

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	reserved						entry_point_address									
Reset	000000						0000000000									

The code entry point of Uc1Ch1 is the 44th code RAM line of the channel 1.

Table 12. Uc1_entry_point registers (0x10B) of channel 1

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	reserved						entry_point_address									
Reset	000000						0000101100									

The microcore Uc0Ch1 must be set up to run the two microcores of the channel as each microcore drives an injection bank.

Both microcores are enabled by setting the pre_flash enable bit and the en_dual_uc bit to logic 1.

Table 13. Flash_enable register (0x100) of channel 1

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
Name	reserved									checksum_disable	flash_enable	pre_flash_enable	en_dual_uc	dual_uc_failure	chksum_irq_en	chksum_failure	
Value	0000					0	0	0	0	0	0	0	1	1	0	0	0

5.1.2.3 Diagnosis configuration registers

The high-side and low-side drivers must be directly controlled by the microcores. Consequently the output_routing fields of the high-side and low-side drivers output configuration register must be set to the value 15.

Table 14. Hsx_output_config registers (0x155, 0x158, 0x15B, 0x15E)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	reserved							dead_time				output_routing				inv
Reset	000000000							0000				1111				0

Table 15. Lsx_output_config registers (0x142, 0x145, 0x148, 0x14B)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	reserved											output_routing				inv
Value	000000000000											1111				0

5.1.3 Injection banks management algorithm

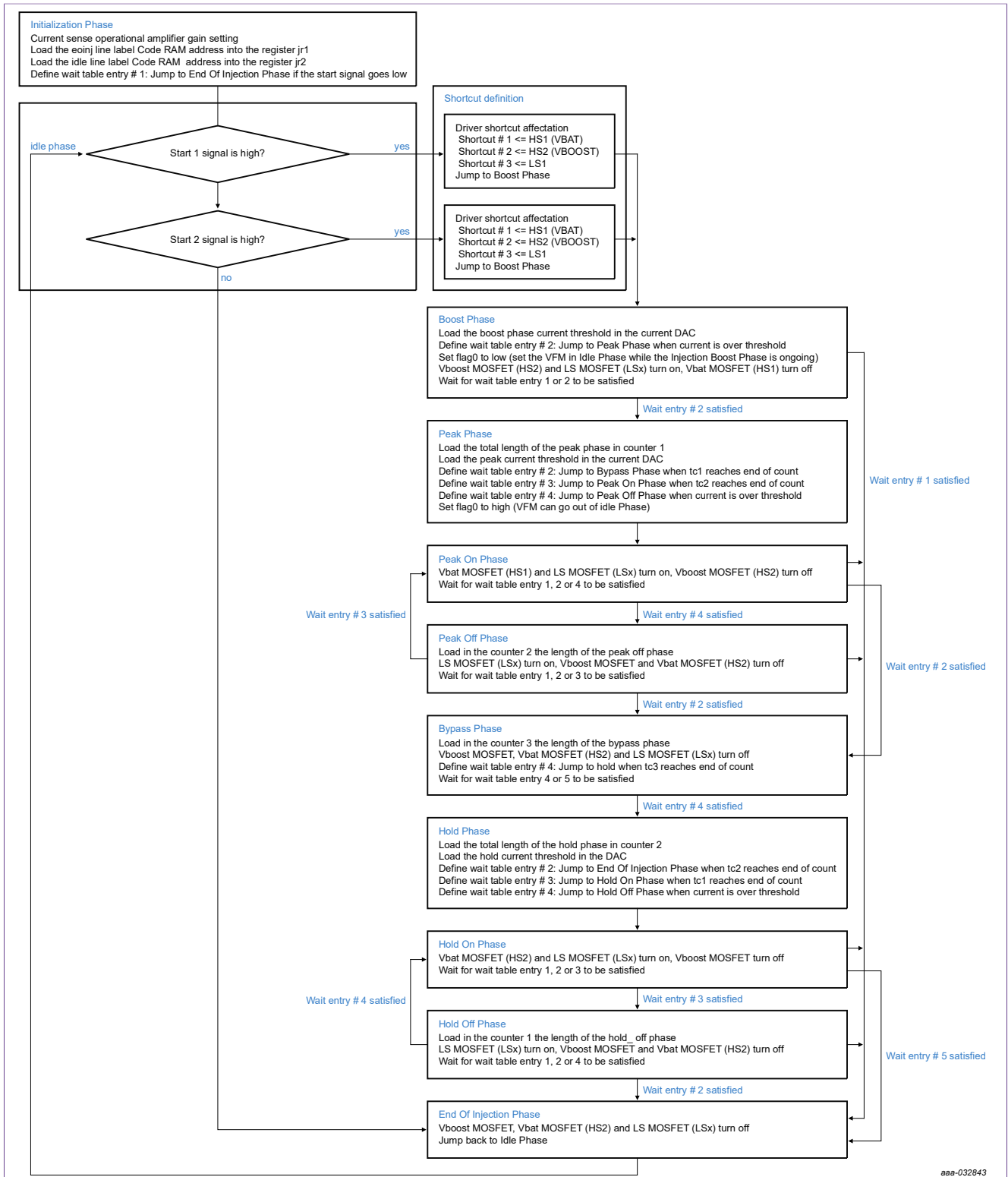


Figure 4. Algorithm example for a bank of two injectors

Refer to [Injection banks management source code](#).

5.2 DC-to-DC management

In variable frequency mode, on/off switching is triggered by the sense current rising above an upper current threshold and falling below a lower current threshold. This mode uses a hysteretic current control loop within a hysteretic voltage control loop. Once the current thresholds are programmed, hardware controls the current regulation loop, while software (microcode) controls the voltage regulation loop. Duty cycle and frequency vary with operating conditions.

The code dedicated to the boost converter regulation loop is loaded into the code RAM 2. This code is executed independently by the microcores Uc0Ch2.

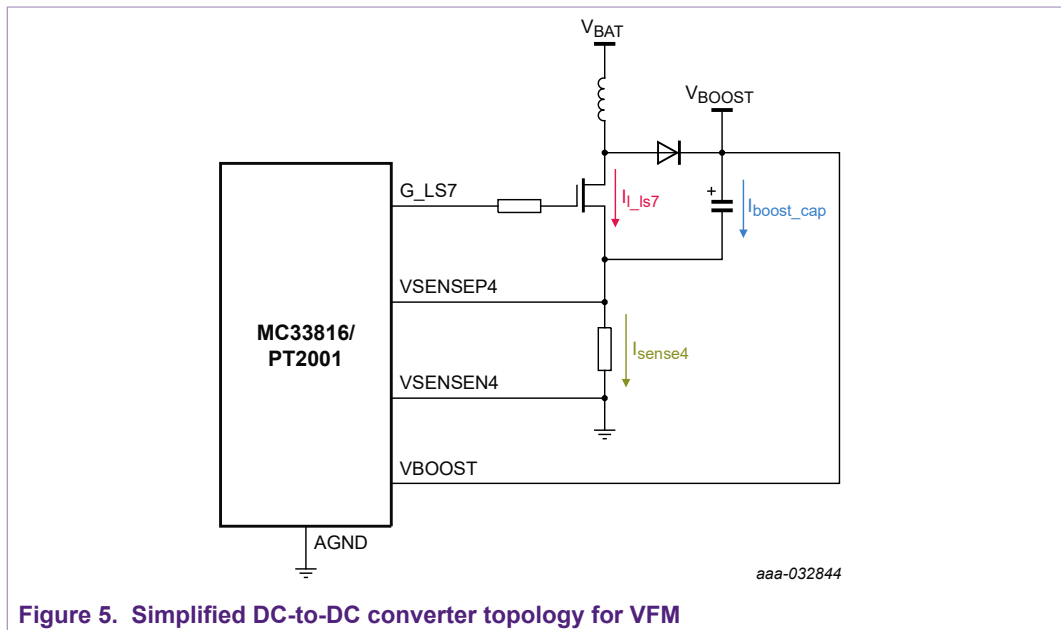


Figure 5. Simplified DC-to-DC converter topology for VFM

At boost startup, the current through the inductor oscillates. This current is maintained between a current lower to the inductor saturation current and a positive current close to zero by turning the low-side switch on/off. When this switch is on, the current grows through the sense resistor and the low-side switch. When the switch is open, the current decays through the diode and loads the output capacitor. It increases the voltage until the V_{BOOST} voltage reaches the V_{BOOST_HIGH} threshold. This phase uses the asynchronous mode and the current modulation is managed by an independent circuitry enabled by the microcore.

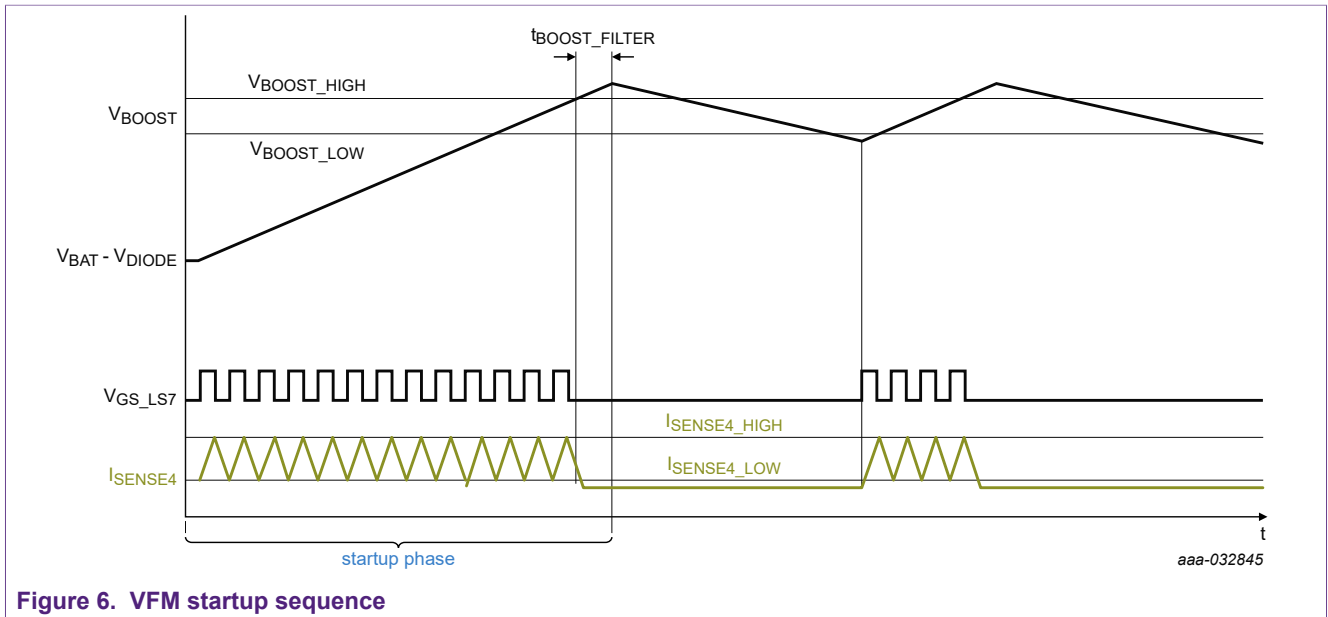


Figure 6. VFM startup sequence

When the V_{BOOST_HIGH} threshold is reached, the synchronous mode is enabled. In this case, the microcore takes the direct control of the low-side switch. The low-side switch is turned off until the boost voltage goes below the V_{BOOST_LOW} threshold.

Each time the V_{BOOST_HIGH} threshold is reached, the V_{BOOST_LOW} threshold is set up. The synchronous mode is activated after a t_{BOOST_FILTER} filter time required by the voltage comparator circuitry enablement.

Each time the boost voltage falls below the V_{BOOST_LOW} threshold the V_{BOOST_HIGH} threshold is set up. The asynchronous mode is activated after a t_{BOOST_FILTER} filter time.

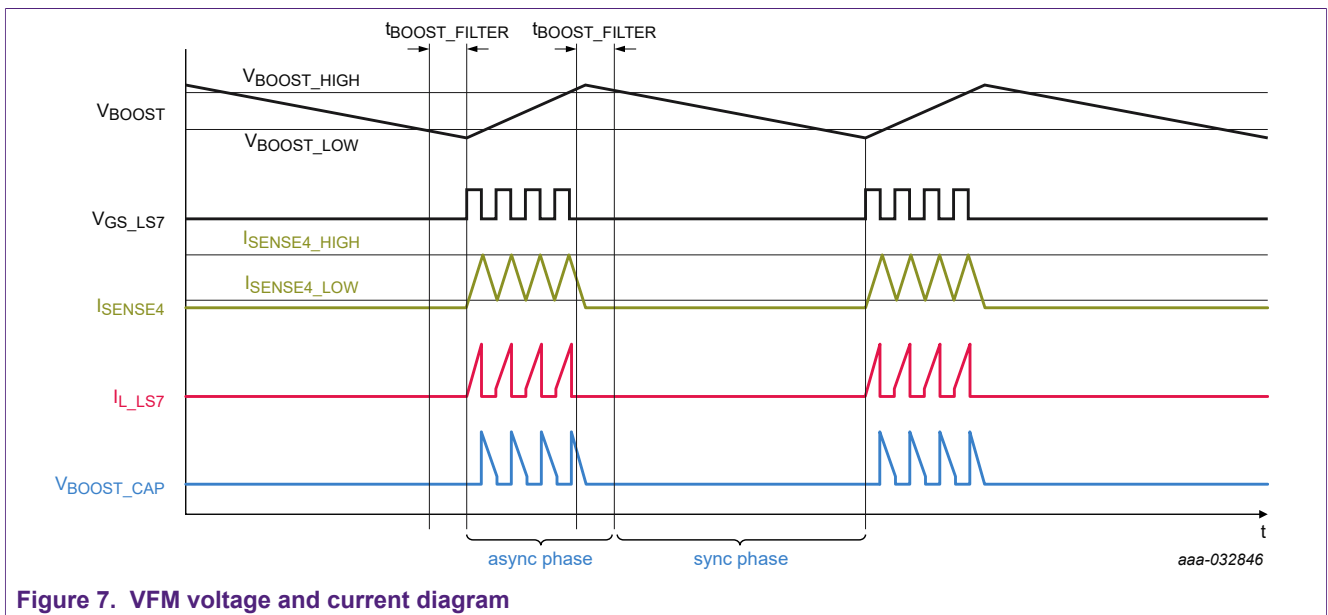


Figure 7. VFM voltage and current diagram

Table 16. Example of VFM DC-to-DC converter key parameters

Parameter name	Description	Value
V _{BOOST_HIGH}	V _{BOOST} voltage HIGH threshold	65.31 V
V _{BOOST_LOW}	V _{BOOST} voltage LOW threshold	64.69 V
I _{SENSE4_HIGH}	HIGH current threshold	3.44 A
I _{SENSE4_LOW}	LOW current threshold	0.41 A

In the present case, most of the code branches (jump) are managed according to the V_{BOOST} voltage and the flag0 state with the wait table. The wait table rows are affected as shown in [Table 17](#) and are changed according to the actuation phase.

Table 17. Example of wait table definition for the fuel pump drive

Phase	Async phase (dcdc_on)	Sync phase (dcdc_off)	Idle phase
Row 1	if flag0 is LOW, then jump to idle phase	if flag0 is LOW, then jump to idle phase	-
Row 2	-	if V _{BOOST} < V _{BOOST_LOW} , then jump to async phase	-
Row 3	if V _{BOOST} > V _{BOOST_HIGH} , then jump to sync phase	-	-
Row 4	-	-	-
Row 5	-	-	-

To avoid regulation disturbances, the boost voltage regulation is stopped by the mean of the internal flag 0 when an injection phase starts.

The t_{BOOST_FILTER} time is defined in the Boost_filter register (0x19D). This filter time and type can be adjusted to improve the V_{BOOST} voltage stability.

Table 18. Boost_filter register (0x19D)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	reserved			filter_type	boost_fbk_filter											
Value	000			0	000000000000											

5.2.1 DC-to-DC management registers setup

The MC33816/PT2001 registers are set up according to their default states, unless defined by the following.

5.2.1.1 IO configuration registers

The Uc0Ch2 must have access to the pre-driver LS7 only.

Table 19. Out_acc_uc0_ch2 register (0x186)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	reserved				acc_uc0_ch1_ls7	acc_uc0_ch1_ls6	acc_uc0_ch1_ls5	acc_uc0_ch1_ls4	acc_uc0_ch1_ls3	acc_uc0_ch1_ls2	acc_uc0_ch1_ls1	acc_uc0_ch1_hs5	acc_uc0_ch1_hs4	acc_uc0_ch1_hs3	acc_uc0_ch1_hs2	acc_uc0_ch1_hs1
Value	0000				1	0	0	0	0	0	0	0	0	0	0	0

The Uc0Ch2 must have access to the current sense feedback 4L and 4H.

Table 20. Cur_block_access_2 register (0x189)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
Name	reserved						acc_uc1_ch2_curr4h_4neg	acc_uc1_ch2_curr4l	acc_uc1_ch2_curr3	acc_uc1_ch2_curr2	acc_uc1_ch2_curr1	acc_uc0_ch2_curr4h_4neg	acc_uc0_ch2_curr4l	acc_uc0_ch2_curr3	acc_uc0_ch2_curr2	acc_uc0_ch2_curr1	
Value	000000						0	0	x	0	0	1	1	0	0	0	

5.2.1.2 Diagnosis configuration registers

The low-side driver 7 must be directly controlled by the microcore Uc0Ch2. Consequently, the output_routing fields of its output configuration register must be set to the value 15.

Table 21. Ls7_output_config register (0x152)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	reserved										fast_dcdc_en	output_routing				inv
Value	0000000000										0	1111				0

5.2.2 DC-to-DC management algorithm

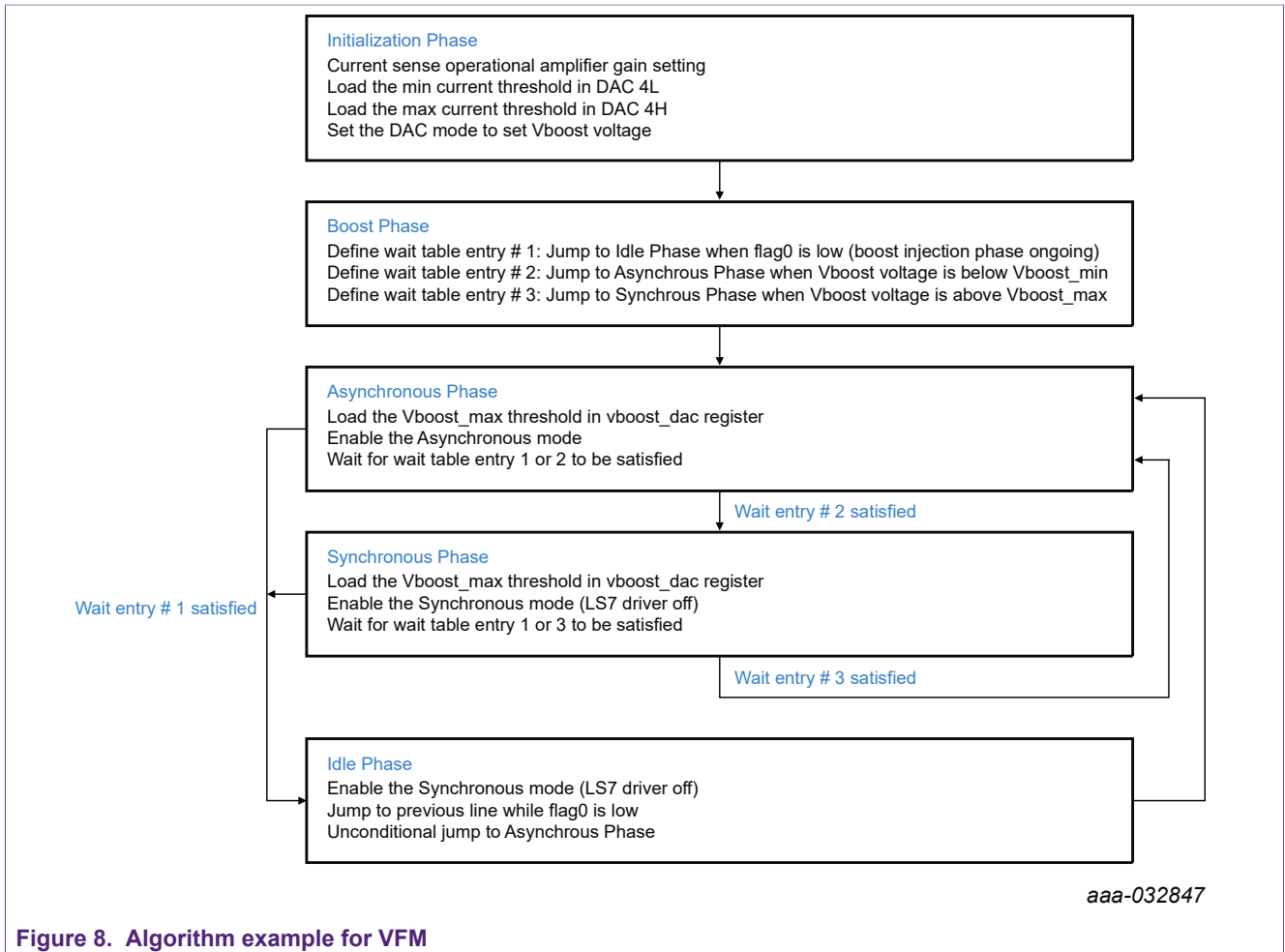


Figure 8. Algorithm example for VFM

Refer to [DC-to-DC management source code](#).

5.3 Fuel pump drive

The current profile is managed to generate an initial high current peak. The current is maintained while the START5 pin keeps the pump running to the end of actuation (EOA).

The code dedicated to the pump driving is loaded into the code RAM 2. This code is executed by the microcore Uc1Ch2. The microcore generates a current profile, as described by the following, per the START5 pin state.

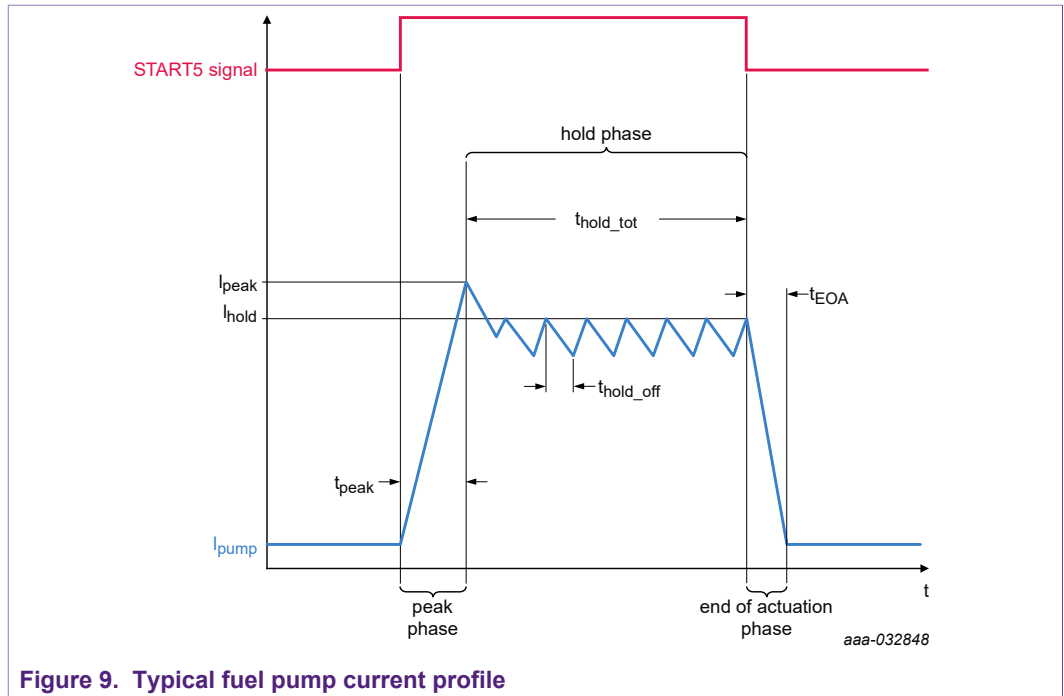


Figure 9. Typical fuel pump current profile

When a rising edge is detected on a START5 pin, the pump actuation starts with the peak phase.

This profile can be stopped at any time by a falling edge detected on the START5 pin, where the EOA phase is executed.

During the peak phase, the corresponding low-side driver is simultaneously switched on with the high-side switch connected to the V_{BAT} voltage. If the peak current target I_{peak} is reached, the hold phase begins.

During the hold phase, the low-side driver is simultaneously switched on with the high-side switch connected to the V_{BAT} voltage. If the hold current target I_{hold} is reached, the high-side driver is switched off and the current recirculates through the diodes connected to VBAT and ground for the fixed time t_{hold_off} . The high-side driver is then switched on again. This cycle repeats until the SATR5 pin goes LOW or the internal counter reaches its terminal value [t_{hold_tot} (timeout)]. The EOA is forced if no falling edge is detected on the START5 pin.

All the current thresholds and timings are accessed in the data RAM. The typical values are the following, but must be defined according to the current profile expected.

Table 22. Example of fuel pump drive key parameters

Parameter name	Description	Value
I_{peak}	current threshold in peak phase	4.79 A
I_{hold}	current threshold in hold phase	3.27 A
t_{hold_off}	fixed time for high-side switch off in hold phase	10 μ s
t_{hold_tot}	fixed time for end of hold phase (timeout)	10 ms

In this case, most of the code branches (jump) are managed according to the counters end of count and the current threshold by the means of the wait table. The wait table rows are affected, as shown in [Table 23](#), and are changed according to the actuation phase.

Table 23. Example of wait table definition for the fuel pump drive

Phase	Peak phase	Hold phase	EOA phase
Row 1	if STARTx goes LOW, then jump to EOA phase	if STARTx goes LOW, then jump to EOA phase	-
Row 2	if the current reaches I_{peak} , then jump to hold phase	if t_{hold_tot} is reached, then jump to EOA phase	-
Row 3	-	if t_{hold_off} is reached, then jump to hold on phase (sub phase)	-
Row 4	-	if I_{hold} is reached, then jump to hold off phase (sub phase)	-
Row 5	-	-	-

5.3.1 Fuel pump drive registers setup

The Uc1Ch2 must have access to the pre-drivers HS5 and LS5.

5.3.2 IO configuration registers

Table 24. Out_acc_uc1_ch2 register (0x187)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	reserved				acc_uc1_ch2_ls7	acc_uc1_ch2_ls6	acc_uc1_ch2_ls5	acc_uc1_ch2_ls4	acc_uc1_ch2_ls3	acc_uc1_ch2_ls2	acc_uc1_ch2_ls1	acc_uc1_ch2_hs5	acc_uc1_ch2_hs4	acc_uc1_ch2_hs3	acc_uc1_ch2_hs2	acc_uc1_ch2_hs1
Value	0000				0	0	1	0	0	0	0	1	0	0	0	0

The Uc1Ch2 must have access to the current sense feedback # 3.

Table 25. Cur_block_access_2 register (0x189)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	reserved						acc_uc1_ch2_curr4h_4neg	acc_uc1_ch2_curr4l	acc_uc1_ch2_curr3	acc_uc1_ch2_curr2	acc_uc1_ch2_curr1	acc_uc0_ch2_curr4h_4neg	acc_uc0_ch2_curr4l	acc_uc0_ch2_curr3	acc_uc0_ch2_curr2	acc_uc0_ch2_curr1
Value	000000						0	0	1	0	0	x	x	0	0	0

5.3.2.1 Channel 2 configuration registers

The pump is driven according to the logic level of the START5 pin. A HIGH level on START5 drives the pump on, while a LOW level stops the pump. The microcore Uc1Ch2 must be enabled by the START5 pin. Consequently, the Start_config_reg register of channel 2 (0x124) must be set up.

Table 26. Start_config_reg register (0x124)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	reserved		smart_start_uc1	smart_start_uc0	start6_sens_uc1	start5_sens_uc1	start4_sens_uc1	start3_sens_uc1	start2_sens_uc1	start1_sens_uc1	start6_sens_uc0	start5_sens_uc0	start4_sens_uc0	start3_sens_uc0	start2_sens_uc0	start1_sens_uc0
Value	00		0	0	0	1	0	0	0	0	0	0	0	0	0	0

The Code_width register and the two checksum value registers must be set to verify permanently the code integrity. The checksum is recalculated in the MC33816/PT2001 at runtime, each time a microcode line is executed. The code width and checksum values are provided for a DC-to-DC converter regulation code and a pump drive code.

Table 27. Code_width register (0x127)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	reserved						code_width									
Value	-						0000100111									

Table 28. Checksum_h register (0x128)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	checksum_high															
Reset	0100000100010100															

Table 29. Checksum_l register (0x129)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	checksum_low															
Reset	1010101110100001															

The code entry point of Uc0Ch2 is logic 0 the first line executed, is the first code RAM line of the channel 2.

Table 30. Uc0_entry_point register (0x12A) of channel 2

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	reserved						entry_point_address									
Reset	000000						0000000000									

The code entry point of Uc1Ch2 is at the 16th code RAM line of the channel 2.

Table 31. Uc1_entry_point register (0x12B) of channel 2

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	reserved							entry_point_address								
Reset	000000							0000010000								

The registers must be set up to run the two microcores of the channel 2 as the first microcode drives the DC-to-DC converter, and the second microcore drives the fuel pump.

Both microcores are enabled by setting the pre_flash enable bit and the en_dual_uc bit to logic 1.

Table 32. Flash_enable register (0x120) of channel 2

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	reserved							checksum_disable	flash_enable	pre_flash_enable	en_dual_uc	dual_uc_failure	chksum_irq_en	chksum_failure		
Value	0000			0	0	0	0	0	0	1	1	0	0	0		

5.3.2.2 Diagnosis configuration registers

The high-side and low-side drivers must be directly controlled by the microcore Uc1Ch2. Consequently, the output_routing fields of the high-side and low-side drivers output configuration register must be set to the value 15.

Table 33. Hs5_output_config register (0x161)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	reserved							dead_time			output_routing			inv		
Reset	000000000							0000			1111			0		

Table 34. Lsx_output_config registers (0x14E, 0x151)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	reserved											output_routing		inv		
Value	00000000000											1111		0		

5.3.3 Fuel pump drive algorithm

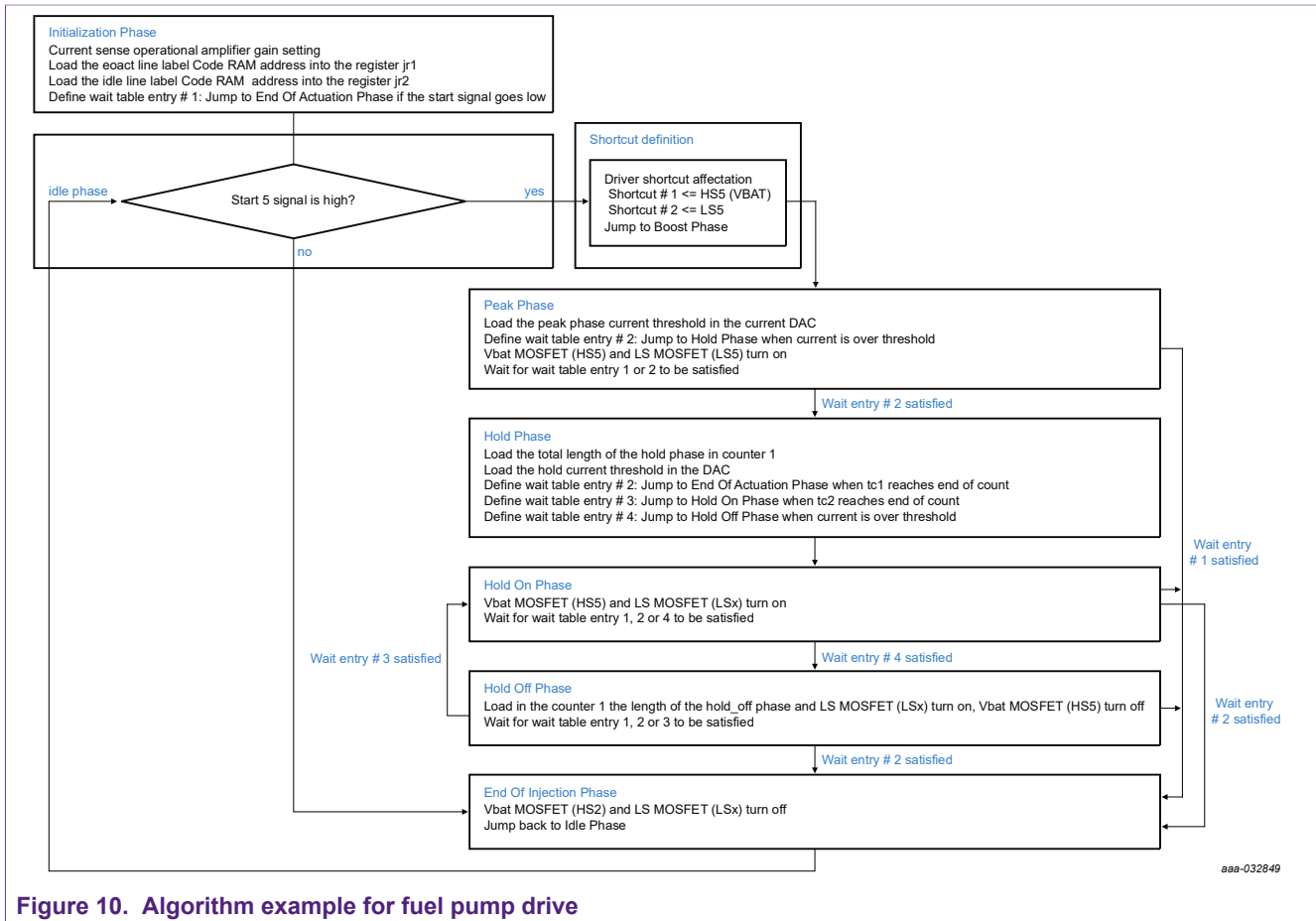


Figure 10. Algorithm example for fuel pump drive

Refer to [Fuel pump drive source code](#).

6 PCB layout recommendations

6.1 Ground connections

The MC33816/PT2001 exposed pad must be connected to the printed-circuit board (PCB) ground. All the grounds (AGND, DGND, and PGND) must be 'in star' or considering a unique ground layer, such as to minimize the introduction of offset and noise mainly in the signal return lines.

6.2 Sense resistors connection

The sense resistors layout must be considered with special care, to sense the voltage as close as possible to the resistor terminations.

Balanced series resistance, induced by the layout, between the sense resistor positive termination to the VSENSEPx and the sense resistor negative termination to the VSENSEPx pin is recommended. The balance can be achieved by implementing similar line lengths.

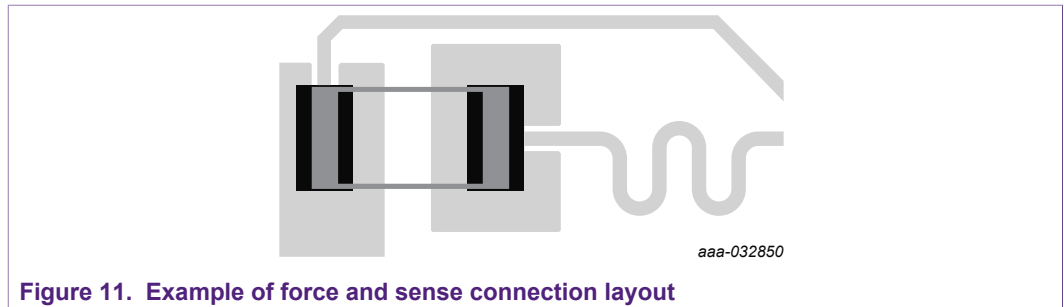


Figure 11. Example of force and sense connection layout

It is highly recommended to place the sense resistor as close as possible to its corresponding low-side MOSFET transistor.

6.3 Drain and source signal connection

The high-side source signals (S_HSx) must be connected as close as possible to its corresponding high-side MOSFET transistor source pin.

The low-side drain signals (G_LSx) must be connected as close as possible to its corresponding high-side MOSFET transistor source pin.

7 Application source code

7.1 Injection banks management source code

```

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* ### Channel 1 - uCore0 controls the injectors 1 and 2 ###

* ### Variables declaration ###

* Note: The data are stored into the dataRAM of the channel 1.
* Note: The Thold_tot variable defines the current profile time out. The active STARTx pin is expected to
toggle in is low state before this time out.

* ### Initialization phase ###
init0:      stgn gain8.68 sssc;          * Set the gain of the opamp of the current measure
block 1
            ldjrl eoinj0;              * Load the eoinj line label Code RAM address into the
register jrl
            ldjr2 idle0;              * Load the idle line label Code RAM address into the
register jr2
            cwef jrl _start row1;     * If the start signal goes low, go to eoinj phase

* ### Idle phase- the uPC loops here until start signal is present ###
idle0:      cwer CheckStart start row2; * Define entry table for high start pin
            stoc on sssc;             * Turn ON off comp
WaitLoop:   wait row2;                * uPC is stuck here for almost the whole idle time
CheckStart: joslr inj1_start start1;  * Jump to inj1 if start 1 is high
            joslr inj2_start start2;  * Jump to inj2 if start 2 is high
            jmpwr WaitLoop;

* ### Shortcuts definition per the injector to be actuated ###
inj1_start: dfsct hs1 hs2 ls1;        * Set the 3 shortcuts: VBAT, VBOOST, LS
            jmpwr boost0;             * Jump to launch phase

inj2_start: dfsct hs1 hs2 ls2;        * Set the 3 shortcuts: VBAT, VBOOST, LS
            jmpwr boost0;             * Jump to launch phase

* ### Launch phase enable boost ###
boost0:     stoc off sssc;            * Turn OFF offset compensation
            *bias all on;*           * Enable all biasing structures, kept ON even during
actuation
            load Iboost dac_sssc_ofs; * Load the boost phase current threshold in the
current DAC
            cwer peak0 ocur row2;    * Jump to peak phase when current is over threshold
            stf low b0;              * set flag0 low to force the DC-DC converter in idle
mode
            stos off on on;          * Turn VBAT off, BOOST on, LS on
            wait row12;              * Wait for one of the previously defined conditions

```

```

* ### Peak phase continue on Vbat ###
peak0:    ldcd rst _ofs keep keep Tpeak_tot c1; * Load the length of the total peak phase in counter 1
          stoc off off on; * Turn VBAT off, BOOST off, LS on
          load Ipeak dac_sssc_ofs; * Load the peak current threshold in the current DAC
          cwer bypass0 tc1 row2; * Jump to bypass phase when tc1 reaches end of count
          cwer peak_on0 tc2 row3; * Jump to peak_on when tc2 reaches end of count
          cwer peak_off0 ocur row4; * Jump to peak_off when current is over threshold
          stf high b0; * set flag0 high to release the DC-DC converter idle

mode
peak_init0: cwer peak_off0 _ocur row5; * Define wait until current is discharge and go lower
            than Ipeak
            wait row125;

peak_on0:  stoc on off on; * Turn VBAT on, BOOST off, LS on
            wait row124; * Wait for one of the previously defined conditions

peak_off0: ldcd rst ofs keep keep Tpeak_off c2; * Load in the counter 2 the length of the peak_off
            phase
            stoc off off on; * Turn VBAT off, BOOST off, LS on
            wait row123; * Wait for one of the previously defined conditions

* ### Bypass phase ###
bypass0:  ldcd rst ofs keep keep Tbypass c3; * Load in the counter 3 the length of the off_phase
            phase
            stoc off off off; * Turn VBAT off, BOOST off, LS off
            cwer hold0 tc3 row4; * Jump to hold when tc3 reaches end of count
            wait row14; * Wait for one of the previously defined conditions

* ### Hold phase on Vbat ###
hold0:    ldcd rst _ofs keep keep Thold_tot c1; * Load the length of the total hold phase in counter
            2
            load Ihold dac_sssc_ofs; * Load the hold current threshold in the DAC
            cwer eoinj0 tc1 row2; * Jump to eoinj phase when tc1 reaches end of count
            cwer hold_on0 tc2 row3; * Jump to hold_on when tc2 reaches end of count
            cwer hold_off0 ocur row4; * Jump to hold_off when current is over threshold

hold_on0: stoc on off on; * Turn VBAT on, BOOST off, LS on
            wait row124; * Wait for one of the previously defined conditions

hold_off0: ldcd rst _ofs keep keep Thold_off c2; * Load the length of the hold off phase in counter 1
            stoc off off on; * Turn VBAT off, BOOST off, LS on
            wait row123; * Wait for one of the previously defined conditions

* ### End of injection phase ###
eoinj0:   stoc off off off; * Turn VBAT off, BOOST off, LS off
            stf high b0; * set flag0 to high to release the DC-DC converter
            idle mode * Jump back to idle phase
            jmpf jr2;

* ### End of Channel 1 - uCore0 code ###
*****

* ### Channel 1 - uCore1 controls the injectors 3 and 4 ###

* ### Variables declaration ###

* Note: The data that defines the profiles are shared between the two microcores.

* ### Initialization phase ###
init1:    stgn gain8.68 sssc; * Set the gain of the opamp of the current measure
            block 2
            ldjrl eoinj1; * Load the eoinj line label Code RAM address into the
            register jrl * Load the idle line label Code RAM address into the
            ldjr2 idle1; * Load the idle line label Code RAM address into the
            register jr2 * If the start signal goes low, go to eoinj phase
            cwef jrl _start row1;

* ### Idle phase- the uPC loops here until start signal is present ###
idle1:    cwer CheckStart1 start row2; * Define entry table for high start pin
            stoc on sssc; * Turn ON offset compensation
            WaitLoop1: wait row2; * uPC is stuck here for almost the whole idle time
            CheckStart1:joslr inj3_start start3; * Jump to inj1 if start 1 is high
            joslr inj4_start start4; * Jump to inj2 if start 2 is high
            jmpr WaitLoop1;

* ### Shortcuts definition per the injector to be actuated ###
inj3_start: dfscst hs3 hs4 ls3; * Set the 3 shortcuts: VBAT, VBOOST, LS
            jmpr boost1; * Jump to launch phase

inj4_start: dfscst hs3 hs4 ls4; * Set the 3 shortcuts: VBAT, VBOOST, LS
            jmpr boost1; * Jump to launch phase

* ### Launch phase enable boost ###
boost1:    stoc off sssc; * Turn OFF offset compensation
            load Iboost dac_sssc_ofs; * Load the boost phase current threshold in the
            current DAC * Jump to peak phase when current is over threshold
            cwer peak1 ocur row2; * set flag0 low to force the DC-DC converter in idle
            stf low b0;

mode
            stoc off on on; * Turn VBAT off, BOOST on, LS on
            wait row12; * Wait for one of the previously defined conditions

* ### Peak phase continue on Vbat ###
peak1:    ldcd rst _ofs keep keep Tpeak_tot c1; * Load the length of the total peak phase in counter 1
            stoc off off on; * Turn VBAT off, BOOST off, LS on
            load Ipeak dac_sssc_ofs; * Load the peak current threshold in the current DAC
    
```

```

cwer bypass1 tc1 row2; * Jump to bypass phase when tc1 reaches end of count
cwer peak_on1 tc2 row3; * Jump to peak_on when tc2 reaches end of count
cwer peak_off1 ocur row4; * Jump to peak_off when current is over threshold
stf high b0; * set flag0 high to release the DC-DC converter idle

mode
peak_init1: cwer peak_off1 _ocur row5; * Define wait until current is discharge and go lower
than Ipeak
wait row125;

peak_on1: stos on off on; * Turn VBAT on, BOOST off, LS on
wait row124; * Wait for one of the previously defined conditions

peak_off1: ldcd rst ofs keep keep Tpeak_off c2; * Load in the counter 2 the length of the peak_off
phase
stos off off on; * Turn VBAT off, BOOST off, LS on
wait row123; * Wait for one of the previously defined conditions

* ### Bypass phase ###
bypass1: ldcd rst ofs keep keep Tbypass c3; * Load in the counter 3 the length of the off_phase
phase
stos off off off; * Turn VBAT off, BOOST off, LS off
cwer hold1 tc3 row4; * Jump to hold when tc3 reaches end of count
wait row14; * Wait for one of the previously defined conditions

* ### Hold phase on Vbat ###
hold1: ldcd rst _ofs keep keep Thold_tot c1; * Load the length of the total hold phase in counter
2
load Ihold dac_sssc_ofs; * Load the hold current threshold in the DAC
cwer eoinj1 tc1 row2; * Jump to eoinj phase when tc1 reaches end of count
cwer hold_on1 tc2 row3; * Jump to hold_on when tc2 reaches end of count
cwer hold_off1 ocur row4; * Jump to hold_off when current is over threshold

hold_on1: stos on off on; * Turn VBAT on, BOOST off, LS on
wait row124; * Wait for one of the previously defined conditions

hold_off1: ldcd rst _ofs keep keep Thold_off c2; * Load the length of the hold_off phase in counter 1
stos off off on; * Turn VBAT off, BOOST off, LS on
wait row123; * Wait for one of the previously defined conditions

* ### End of injection phase ###
eoinj1: stos off off off; * Turn VBAT off, BOOST off, LS off
stf high b0; * set flag0 to high to release the DC-DC converter

idle mode
jmpf jr2; * Jump back to idle phase

* ### End of Channel 1 - uCore1 code ###

```

7.2 DC-to-DC management source code

```

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* ### Channel 2 - uCore0 controls dc-dc ###

* ### Initialization phase ###
init0: stgn gain5.8 ossc;
load Iboost_L dac_osscc_ofs; *load DAC 4 L with low Vboost current
load Iboost_H dac4h4n_ofs; *load DAC 4H with high Vboost current
stdm null; *Set DAC access mode to Vboost
cwer idle0 _f0 row1; *if flag 0 is low turn Off the boost
cwer dcdcon _vb row2; *if vboost lower than vboost low then turn on boost
cwer dcdcoff vb row3; *if vboost higher than vboost high then turn off boost

dcdcon: load Vboost_H dac4h4n_ofs; *set Vboost high
stdcctl async; *set dcDc to async
wait row13;

dcdcoff: load Vboost_L dac4h4n_ofs; *set Vboost low
stdcctl sync; *set dcDc to sync
wait row12;

idle0: stdcctl sync;
joer idle0 _f0;
jmp r dcdcoff;

* ### End of Channel 2 - uCore0 code ###

```


7.3 Fuel pump drive source code

```

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* ### Channel 2 - uCore1 drives fuel pump ###

* ### Initialization phase ###
init1:      stgn gain19.4 ossc;          * Set the gain of the opamp of the current measure
block 1     ldjrl eoact1;              * Load the eoinj line label Code RAM address into the
register jr1 ldjr2 idle1;              * Load the idle line label Code RAM address into the
register jr2 cwef jr1 _start row1;     * If the start signal goes low, go to eoinj phase

* ### Idle phase- the uPC loops here until start signal is present ###
idle1:     joslr act5_start start5;    * Perform an actuation on act5 if start 5 (only) is
active     joslr act6_start start6;    * Perform an actuation on act5 if start 5 (only) is
active     jmpf jr1;                   * If more than 1 start active at the same time(or
none), no actuation

* ### Shortcuts definition per the injector to be actuated ###
act5_start: dfact hs5 ls5 undef;      * Set the 2 shortcuts: VBAT, LS
           jmpr peak1;

act6_start: dfact hs5 ls6 undef;      * Set the 2 shortcuts: VBAT, LS

* ### Launch peak phase on bat ###
peak1:     load lpeak dac_osscc _ofs;  * Load the boost phase current threshold in the
current DAC
           cwer hold1 cur3 row2;      * Jump to peak phase when current is over threshold
           stos on on keep;           * Turn VBAT off, BOOST on, LS on
           wait row12;                * Wait for one of the previously defined conditions

* ### Hold phase on Vbat ###
hold1:     ldcd rst_ofs keep keep Thold_tot c1; * Load the length of the total hold phase in counter
           load lhold dac_osscc _ofs;  * Load the hold current threshold in the DAC
           cwer eoact1 tc1 row2;      * Jump to eoinj phase when tc1 reaches end of count
           cwer hold_on1 tc2 row3;    * Jump to hold_on when tc2 reaches end of count
           cwer hold_off1 cur3 row4;  * Jump to hold_off when current is over threshold

hold_on1:  stos on on keep;           * Turn VBAT on, LS on
           wait row124;               * Wait for one of the previously defined conditions

hold_off1: ldcd rst_ofs off on Thold_off c2; * Load the length of the hold_off phase in counter 1
           and turn VBAT off, LS on
           wait row123;               * Wait for one of the previously defined conditions

* ### End of injection phase ###
eoact1:    stos off off keep;         * Turn VBAT off, LS off
           jmpf jr2;                   * Jump back to idle phase

* ### End of Channel 2 - uCore1 code ###

```

8 References

- [1] MC33816 data sheet:
<http://www.nxp.com/MC33816DS>
- [2] PT2001 summary page:
<http://www.nxp.com/PT2001>
- [3] KIT33816FRDMEVM summary page:
<http://www.nxp.com/KIT33816FRDMEVM>
- [4] PT2001 EVB user guide:
<http://www.nxp.com/KTFRDMPT2001EVMUG>

9 Revision history

Table 35. Revision history

Rev	Date	Description
5	20190715	<ul style="list-style-type: none">• Figure 1: updated VBATT pin circuitry• Moved revision history to Section 9.
4	20190329	<ul style="list-style-type: none">• The format of this document has been redesigned to comply with the new identity guidelines of NXP Semiconductors.• Legal texts have been adapted to the new company name where appropriate.• added product type PT2001
3	11/2014	<ul style="list-style-type: none">• Replaced KIT33816AEEVM by KIT33816FRDMEVM• Add a reference link for KT33816FRDMUG
2	9/2014	<ul style="list-style-type: none">• Updated timeout value (tHOLD_TOT) in the example of injection current profile key parameters table• Updated bit names in the Out_acc_uc1_ch2 register (0x187) table
1	1/2013	initial version

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